

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJCD2007A
Package Type :	DFNWB2x3-6L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	13.9803%
Lead Frame	Cu	7440-50-8	96.80%	42.6809%
	Fe	7439-89-6	2.40%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.10%	
	Pb	7439-92-1	0.02%	
	Silver	7440-22-4	0.60%	
Epoxy	Silver	7440-22-4	70.50%	2.2204%
	Epoxy resin	proprietary	20.00%	
	Epoxy resin modifier	proprietary	6.00%	
	dapsone	80-08-0	3.00%	
	substituted silane	proprietary	0.50%	
Gold Wire	Cu	7440-50-8	97.60%	1.4803%
	Pd	7440/5/3	2.40%	
Mold Compound	Epoxy Resin 1	Trade Secret	4.00%	39.6382%
	Epoxy Resin 2	Trade Secret	0.80%	
	Phenolic Resin	Trade Secret	4.00%	
	Metal Hydroxide	Trade Secret	5.00%	
	Carbon black	1333-86-4	0.20%	
	Amorphous silica1	60676-86-0	80.00%	
	Amorphous silica2	7631-86-9	6.00%	
Plating	Tin	7440-31-5	100.00%	4.0296%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.